# UTC UNISONIC TECHNOLOGIES CO., LTD

13N50K **Preliminary Power MOSFET** 

# **13A, 500V N-CHANNEL POWER MOSFET**

#### DESCRIPTION

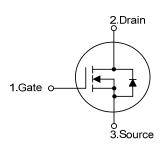
The UTC 13N50K is an N-Channel enhancement mode power MOSFET. The device adopts planar stripe and uses DMOS technology to minimize and provide lower on-state resistance and faster switching speed. It can also withstand high energy pulse under the avalanche and commutation mode conditions.

The UTC 13N50K is ideally suitable for high efficiency switch mode power supply, power factor correction, electronic lamp ballast based on half bridge topology.

# **FEATURES**

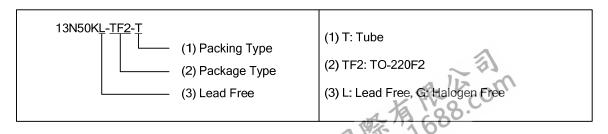
- \*  $R_{DS(ON)}$  <0.48 $\Omega$  @ $V_{GS}$  = 10V
- \* Ultra low gate charge (typical 39nC)
- \* Low reverse transfer Capacitance ( C<sub>RSS</sub> = typical 20pF )
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

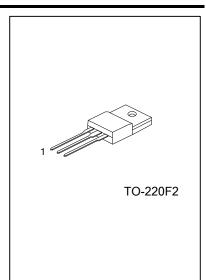
# **SYMBOL**



#### **ORDERING INFORMATION**

Ordering Number		Doolsone	Pin Assignment			Dealing	
Lead Free	Halogen Free	Package	1	2	3	Packing	
13N50KL-TF2-T	13N50KG-TF2-T	TO-220F2	G	D	S	Tube	





www.unisonic.com.tw 1 of 7

# **MARKING INFORMATION**

PACKAGE	MARKING
TO-220F2	UTC 13N50K□ → G: Halogen Free  Lot Code  1



# ■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise specified)

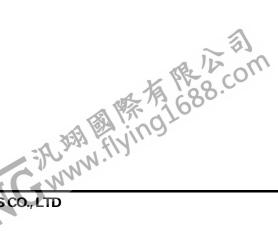
PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	V <sub>DSS</sub>	500	V
Gate-Source Voltage	V <sub>GSS</sub>	±30	V
Continuous Drain Current	I <sub>D</sub>	13	Α
Pulsed Drain Current (Note 2)	I <sub>DM</sub>	52	Α
Avalanche Current (Note 2)	I <sub>AR</sub>	13	Α
Single Pulsed Avalanche Energy (Note 3)	E <sub>AS</sub>	700	mJ
Repetitive Avalanche Energy (Note 2)	E <sub>AR</sub>	17	mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	4.5	V/ns
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	48	W
Junction Temperature	TJ	+150	°C
Storage Temperature	T <sub>STG</sub>	-55~+150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature
- 3. L = 8mH,  $I_{AS}$  = 13A,  $V_{DD}$  = 50V,  $R_{G}$ = 25 $\Omega$  , Starting  $T_J$  = 25 $^{\circ}$ C
- 4.  $I_{SD} \le 13.A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$

# **■ THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	$\theta_{JA}$	62.5	°C/W	
Junction to Case	$\theta_{JC}$	2.58	°C/W	



# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> =25°C, unless otherwise specified)

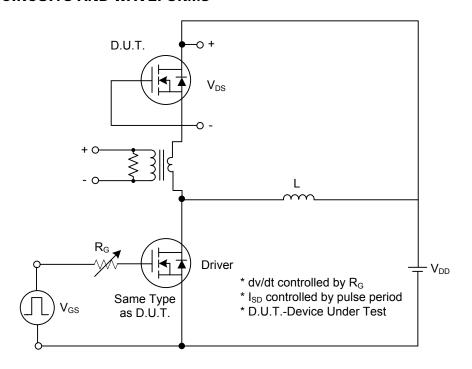
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	500			V		
Drain-Source Leakage Current	I <sub>DSS</sub>	$V_{DS} = 500V, V_{GS} = 0V$			10	μΑ		
Cata Cauran Laglana Current	I <sub>GSS</sub>	$V_{GS} = 30V, V_{DS} = 0V$			100	nΑ		
Gate-Source Leakage Current		$V_{GS} = -30V, V_{DS} = 0V$			-100	nΑ		
Breakdown Voltage Temperature Coefficient	$\triangle BV_{DSS} \! / \triangle T_J$	I <sub>D</sub> =250mA,Referenced to 25°C		0.5		V/°C		
ON CHARACTERISTICS								
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	2.0		4.0	V		
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6.5A		0.42	0.48	Ω		
DYNAMIC CHARACTERISTICS								
Input Capacitance	$C_{ISS}$	\\ -35\\ \\ -0\\		1800	2300	pF		
Output Capacitance	C <sub>OSS</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, -f=1.0MHz		245	320	pF		
Reverse Transfer Capacitance	$C_{RSS}$			25	35	pF		
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	$t_{D(ON)}$			40	90	nS		
Turn-On Rise Time	$t_R$	$V_{DD}$ =250V, $I_{D}$ =13A, $R_{G}$ =25 $\Omega$ (Note 1,2)		140	290	nS		
Turn-Off Delay Time	$t_{D(OFF)}$			100	210	nS		
Turn-Off Fall Time	$t_{F}$			85	180	nS		
Total Gate Charge	$Q_G$	-V <sub>DS</sub> =400V, I <sub>D</sub> =13A, -V <sub>GS</sub> =10 V (Note 1,2)		39	60	nC		
Gate-Source Charge	$Q_GS$			12		nC		
Gate-Drain Charge	$Q_GD$			11		nC		
DRAIN-SOURCE DIODE CHARACTERISTIC	CS AND MAXI	MUM RATINGS						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_{S} = 13 A$			1.4	٧		
Maximum Continuous Drain-Source Diode	1				13	Α		
Forward Current	I <sub>S</sub>				13	А		
Maximum Pulsed Drain-Source Diode	la				52	Α		
Forward Current	I <sub>SM</sub>				52	^		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 13A,$		290		nS		
Reverse Recovery Charge	$Q_{RR}$	dI <sub>F</sub> / dt =100A/μs (Note 1)		2.6		μC		

Notes: 1. Pulse Test : Pulse width≤300µs, Duty cycle≤2%

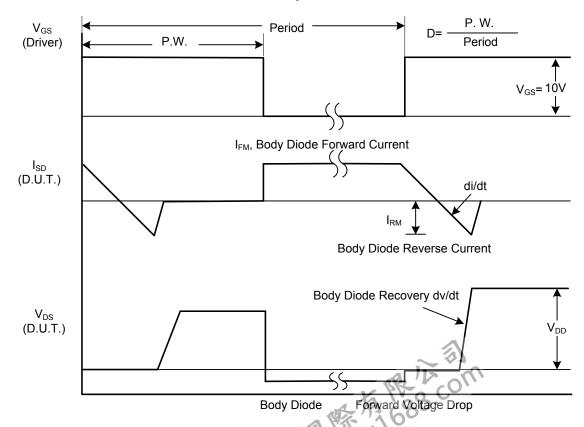


<sup>2.</sup> Essentially independent of operating ambient temperature

# **■ TEST CIRCUITS AND WAVEFORMS**

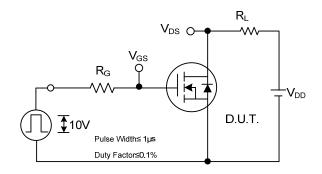


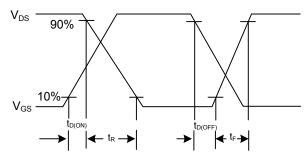
# Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

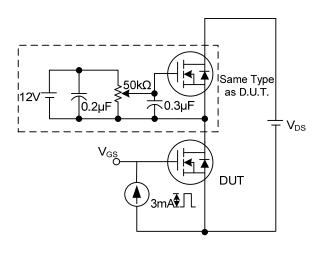
# **TEST CIRCUITS AND WAVEFORMS (Cont.)**

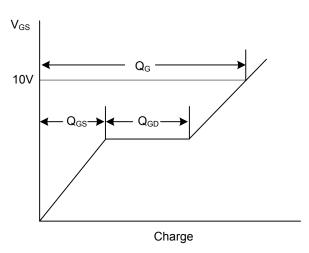




**Switching Test Circuit** 

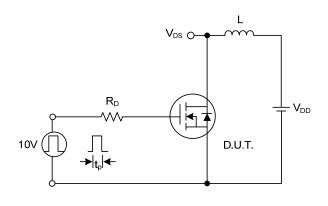
**Switching Waveforms** 

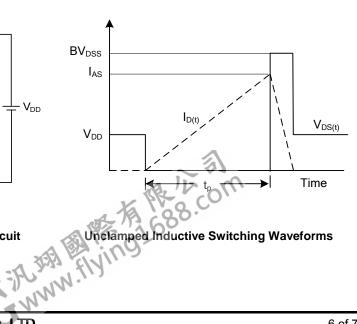




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 





**Unclamped Inductive Switching Test Circuit** 

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